



## SCOPE OF ACCREDITATION

### Electronics

**Zollner Elektronik AG / Plant Untergschwandt**  
Untergschwandt 3  
Rattenberg, 94371  
Germany

This certificate expiration is updated based on periodic audits. The current expiration date and scope of accreditation are listed at: [www.eAuditNet.com](http://www.eAuditNet.com) - Online QML (Qualified Manufacturer Listing).

In recognition of the successful completion of the PRI evaluation process, accreditation is granted to this facility to perform the following:

#### **AC7120 Rev E - Nadcap Audit Criteria for Circuit Card Assemblies (to be used on audits on/after 9 April 2017)**

- 04– General
- 06– Process Control
- 07– Visual Acuity
- 08– Customer Data
- 09– Electrostatic Discharge (ESD)
- 10– Material Management
- 11– Moisture Sensitive Components and Materials
- 12– Kitting
- 13.1– In–Process Verification / Inspection: General
- 13.2– In–Process Verification / Inspection: Visual
- 13.3– In–Process Verification / Inspection: AOI
- 14.1– Secondary Assembly: Mechanical Part Installation
- 14.3– Secondary Assembly: Jumper Wire Installation
- 14.5– Secondary Assembly: Compliant Pin (Press Fit) Connector Installation
- 14.6– Secondary Assembly: Bonding
- 15– Cleanliness
- 16– Final Inspection
- 17– Rework

#### **AC7120/2 - General Soldering of Printed Board Assemblies (to be used on audits on/after 9 April 2017)**

- 03– General

- 04– Electronic Component Preparation for Preassembly Process
- 05.1– Part Placement: General
- 05.2– Part Placement: Manual
- 05.3– Part Placement: Clinched Component Leads
- 06– Gold Removal
- 07– Build Through / Build Short
- 08– Hand Soldering

**AC7120/3 - Plated Through Hole Technology (to be used on audits on/after 9 April 2017)**

- 03.1– Part Placement: Operator–Assisted (Semi–Automated)
- 04– Wave Soldering
- 05– Selective Soldering

**AC7120/4 - Surface Mount Technology (to be used on audits on/after 9 April 2017)**

- 03– Preparation
- 04– Stencil Printing
- 05– Automated Part Placement
- 06– Reflow Soldering

**AC7120/7 - Conformal Coating of Printed Board Assemblies (to be used on audits on/after 9 April 2017)**

- 04– Material
- 05– Material and Equipment Compatibility
- 06– Preparation / Cleaning
- 07– Application / Drying / Curing
- 08– Thickness
- 09– Inspection
- 10– Rework
- 11– Training

**AC7120/9 - Programming (to be used on audits on/after 9 April 2017)**

- 04– General
- 05– Component Programming (Prior to Assembly)
- 06– Circuit Card Assembly Programming

**AC7120/10 - Final Testing (to be used on audits on/after 9 April 2017)**

- 04– General